

(19)



Europäisches Patentamt

European Patent Office

Office européen des brevets

(11) Publication number:

0 197 496

A2

(12)

## EUROPEAN PATENT APPLICATION

(21) Application number: 86104468.3

(51) Int. Cl.<sup>4</sup>: B 29 C 37/00

B 29 C 67/14, B 29 C 43/18

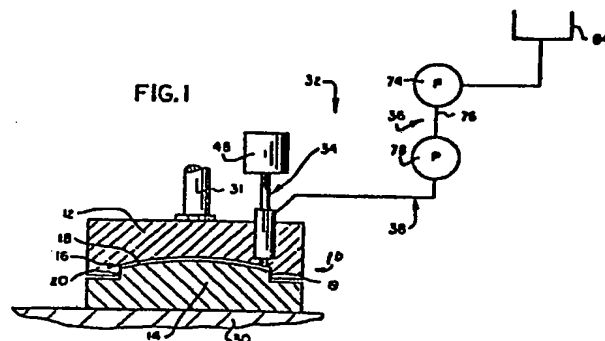
(22) Date of filing: 02.04.86

(30) Priority: 02.04.85 US 718913

(43) Date of publication of application:  
15.10.86 Bulletin 86/42(84) Designated Contracting States:  
AT BE DE FR GB IT LU NL SE(71) Applicant: THE SHERWIN-WILLIAMS COMPANY  
101 Prospect Avenue, N.W.  
Cleveland Ohio 44115-1075(US)(72) Inventor: Ongena, Robert Edmund  
8317 Hilltop Court  
Romeo Michigan 48065(US)(74) Representative: Abitz, Walter, Dr.-Ing. et al,  
Abitz, Morf, Gritschneider, Freiherr von Wittgenstein  
Postfach 86 01 09  
D-8000 München 86(DE)

(54) Molding with in-mold coating.

(57) A method of molding and coating in a mold a thermosetting substrate including the steps of forming the substrate between at least two separable dies which form a mold cavity therebetween, curing the substrate to the point that the substrate is receptive to a coating, injecting the coating into the mold cavity at a pressure substantially in excess of the mold cavity pressure while maintaining the dies in position whereby the coating is forced over the desired surface of the substrate and curing the coated substrate.



1

MOLDING WITH IN-MOLD COATING

5

BACKGROUND OF THE INVENTIONDescription of Prior Art

10

Molding of thermosetting plastics has become widespread. Particularly in the automotive industry where weight is a significant factor, molding of plastic parts for interior parts and exterior panels has become common. As set forth in a brochure MD 79-012 of General Motors entitled "Molded Coating Process and Specifications," exterior class "A" panels are formed of a composite of specialty polyester resins, thickeners, thermoplastic copolymers, mineral fillers, fiber reinforcements, catalysts, and release agents. These materials are commonly combined (with different variations) in a sheet form and are known as "SMC." In the known molding technique of Compression Molding, a piece of SMC of the appropriate size is placed in a mold made up of a fixed and movable die which define a mold cavity therebetween. The dies are nested in the sense that they have side or shear edges which closely interfit and act as a seal during molding.

15

20

25

The dies are forced closed by a press ram under high forces that cause pressures on the substrate up to about 1500 psi. As a practical matter, the initial pressure must be high enough to form the substrate into the shape of the mold cavity. Depending on the size and shape of the part to be formed, different pressures are required. This molding process is commonly carried out at 300°F but different temperatures may be used.

30

35

1

The molded products resulting from Compression Molding can have surface defects, such as surface pits, porosity, sink marks and shrink cracks. In order to cover these defects to produce a class "A" surface, a technique of in-mold coating has been developed. The process for molding and in-mold coating presently includes the following sequence:

10

15

20

25

30

35

- (1) the mold is opened and an SMC charge is placed between the dies in the mold cavity;
- (2) a press ram closes the mold under enough pressure to form or mold the substrate;
- (3) level control cylinders try to maintain the dies in parallel condition while closing;
- (4) after at least partial curing, the press ram releases the pressure;
- (5) cylinders force the mold open;
- (6) an injector shut-off pin for the coating opens;
- (7) the metering pump(s) stroke, injecting the coating;
- (8) the shut-off pin closes;
- (9) the press ram re-pressurizes;
- (10) the level control cylinder readjusts to try to maintain parallelism while reclosing to allow the coating to spread evenly across the part surface;
- (11) the coating is cured; and
- (12) the press ram is released, the dies are separated, and the part is removed.

1

The opening and closing of the mold, the depressurizing and repressurizing, and their accompanying level adjustment are major time delays in the in-mold coating process. A typical example of this process is illustrated in FIGS. 4 and 5 of U.S. patent No. 4,076,788 to Edwin D. Ditto, which is incorporated herein by reference. It is estimated that this opening and closing of the molds take up 5 to 20 percent of the total molding and coating process time. When the millions and millions of parts that are molded yearly are considered, the inefficiency and cost of this opening-closing routine are staggering.

The reopening and reclosing of the mold cause other problems. Opening of the dies causes the flashing around the shear edges to enter the mold cavity. Disturbance of the shear edge may cause an incomplete seal after reclosing. Moreover, the open-close coating method precludes the possibility of using secondary cores or slides in the mold. The slide usually comes in at an angle to one of the dies, and thus cannot be used if the die moves relative to the substrate. Another major limitation of in-mold coating as presently practiced is that it is not readily applicable to injection or reaction injection molding processes. These types of molding processes do not use dies that normally have shear edge construction.

It would be highly desirable to eliminate the secondary opening and closing of the dies from an efficiency and flexibility point of view.

30

35

1

SUMMARY OF THE INVENTION

5 This invention includes the process of molding parts and coating them in the mold. It includes forming a substrate in any mold having at least two separable parts and at least partially curing it to the degree that it has a surface receptive to a coating. The coating is injected into the mold at a high pressure without reopening or reclosing the mold. The coated part is subsequently cured and removed.

10 The elimination of the steps of opening and closing the dies by injecting coating at high pressures greatly increases the efficiency of the process, makes it more reliable, allows the use of secondary cores and slides, and probably makes it applicable to many forms of molding.

15 The time for compression molding a part varies widely with its size and shape. Larger, more complex parts naturally take more time. However, for any given part, it is estimated that the elimination of the opening and closing of the dies and the associated steps will save from 5 to 20 percent of the total molding and coating time. This saving translates to obtaining about the same percentage increase in productivity from existing capital equipment. For capital equipment for which costs often run into the millions of dollars for a single facility, the extra productivity is highly significant.

20 The reliability of in-mold coating to produce consistent, uniform products is also enhanced by this process. All the defects to the part and coating resulting from the reopening and reclosing of the dies are eliminated. Shear edge flash contamination, distortion, loss of the proper seal, and loss of parallelism are all

35

1 undesirable frequent occurrences when the mold is opened  
and closed during the injection of the coating.

5 This improved method of molding and coating  
products has broader application than the previous  
methods. Since the mold is not reopened, cores or slides  
in the die may be used to create different shapes or  
openings in the part. These items previously had to be  
done with a secondary operation. Since the present coat-  
ing process does not include opening the mold during the  
10 curing process, it would appear to be useful in injection  
molding. The same could be said of reaction injection  
molding and other types.

15 The high pressure injection also appears to coat  
more uniformly than low pressure injection. Moreover,  
the use of mechanisms to ensure parallelism of the dies  
does not appear to be necessary for this coating process,  
although it may still be necessary to ensure even flow of  
the substrate in the die cavity.

20

#### BRIEF DESCRIPTION OF THE DRAWINGS

25 FIG. 1 is a schematic representation of the  
compression mold and injection means; and

30 FIGS. 2-6 illustrate a process of compression  
molding utilizing in-mold coating.

35

35

1

DETAILED DESCRIPTION OF THE DRAWINGS

5 The general system of the process of this invention is illustrated in FIG. 1. It includes a mold 10 made up of dies 12,14 which are generally nested in the sense that they form a mold cavity 16 therebetween and have complementary surfaces 17 and 18. The concave surface 17 forms the bottom of the die or cavity 12. The  
10 convex surface 18 forms the upper surface of the lower die 14, also frequently called the "core." "

As illustrated in more detail in FIGS 2 through 6, the shear edges 19 and 20 on the die 14 and 21 and 22 on the die 12 are dimensioned to closely interfit with a  
15 very small dimensional difference. It is important that the shear edges in compression molding are very accurately dimensioned, since the substrate used in the molds goes into the shear edges and, when it begins to cure, acts as a seal.

Horizontal surfaces 23,24 on the lower die 14  
20 interfit with complementary surfaces 26 and 28 on the upper die 12. At times, spacers or stops are used between the dies to ensure parallelism. The lower die 14 sits on a press bed 30 and the upper die 12 is motivated downwardly by a press ram 31. Cylinders or other means  
25 for separating the dies are also built into such machines, but are not shown.

An injection means, generally shown as 32, includes an injector 34, pump means 36, and appropriate conduit system 38. The injector 34 as particularly  
30 shown in FIGS. 2 through 6 includes an actuator 48 of any known type, such as hydraulic or electric. An injector housing 50 surrounds a pin 52 which passes therethrough and is operatively connected to the actuator 48. An

35

1 example of such an injector is Model No. MRF 600-625-250,  
manufactured by The Morrell Co., Inc.. A chamber 70 in  
the housing 50 connects a bore 68 in the die 12 with a  
conduit 72 leading to the pump means 36. Conduit 72 is  
5 part of the conduit system 38.

The chamber 70 is generally complementary with  
the shape of the pin 52, and has appropriate seals  
between it and the pin 52 to ensure fluidtight opera-  
tion. Conduit 38 would normally include the fittings,  
10 hoses, tubes, pipes, etc. which are necessary in this  
type of process. In this particular embodiment, the  
connectors, fittings, and conduits should have an operat-  
ing pressure substantially in excess of the pressures  
generated by the pump of the coating. In this particular  
embodiment, it may mean operating pressures of 5000 or  
15 6000 psi, or even higher.

The pump means 36 includes a first high pressure  
pump 74. Any type of high pressure pump for coating  
means will be applicable, and a typical commercially  
available one would be the Model No. 206-445, manufac-  
20 tured by Graco Co. The output of the pump 74 goes  
through a conduit 76 and to a second high pressure pump,  
or metering pump, which steps up the pressure of the  
coating. The coating may be a one-component system as  
illustrated in FIG. 1, or a two or more component sys-  
25 tem. This invention is not limited to any particular  
type of coating or coating system. The second high  
pressure metering pump may be of any commercially avail-  
able type, such as Model No. 851002000, manufactured by  
The Morrell Company, Inc.

30 One example of coatings that has been found  
successful is a molding coating manufactured by The  
Sherwin-Williams Company and known as Glas-Clad E67 BC



1 10. The general type of coating utilized in the present  
process is illustrated in U.S. patent No. 4,293,659 to  
Svoboda, the disclosure of which is incorporated herein  
by reference.

5 The coatings which are useful in the in-mold  
coating process of this invention include any coating  
which could be polymerized and/or cross-linked within the  
mold. These coatings typically are cured or polymerized  
by free radical and/or condensation polymerization  
10 methods and can include both single-component and two-  
component coatings, as are well-known in the art. Repre-  
sentative coatings include acrylic and acrylic ester  
polymers, saturated and unsaturated polyesters, epoxy  
esters, active hydrogen containing resins cross-linkable  
15 by blocked or free isocyanates and others. If a two-  
component resin system is used, the components are mixed,  
typically by a static mixer such as that made by Kenics  
Corporation, immediately prior to injection into the mold.

The cure time required for the coatings should  
20 be slow enough to allow the coatings to flow over the  
molded part in the mold prior to excessive gelation, but  
short enough to allow substantial curing within the mold-  
ing cycle. Typically, cure times will run from about 15  
to about 100 seconds at mold temperatures of about  
300°F.

25 In addition to the polymerizable components, the  
in-mold coatings may also contain pigments, conductive  
materials such as carbon black, mold release agents such  
as dialkyl phosphates, initiators, catalysts, acceler-  
ators, flow agents, thickeners and other additives.

30 Representative one-component in-mold coatings  
typical of those useful in this invention include those

1 taught in U.S. patents 4,235,833 and 4,239,808 (free radical polymerizable vinyl ester resin/polyvinyl acetate/styrene); U.S. patents 4,293,659 and 4,366,109 (polymerizable blocked isocyanate/ethylenically unsaturated polymer/ethylenically unsaturated monomer); U.S. patent 4,414,173 (polymerizable epoxy-based oligomer/copolymerizable monomer; copolymerizable monoethylenically unsaturated compound/polyvinyl acetate); U.S. patent 4,422,996 (unsaturated monomer solution of a polyurethane polyacrylate and a copolymerizable ethylenically unsaturated monomer solution of an acrylic or methacrylic ester of a diepoxide); and U.S. patent 4,477,405 (an ethylenically unsaturated monomer dispersion of a polymerizable ethylenically unsaturated urea-urethane polymer).

15 Representative two-component coating systems include the coatings taught in U.S. patent 4,081,578 (polyisocyanate/active hydrogen containing resin); and U.S. patent 4,189,517 (diisocyanate/unsaturated polyester/saturated polyester diol Flexibilizer/cross-linking polygol). The teaching of coating materials useful in  
20 in-mold coating in all of these patents is hereby incorporated by reference.

The coating is added to the mold in amounts sufficient to provide coverage of the plastic part to the desired film thickness. Typically, the coating will  
25 provide a final cure film thickness of at least 0.1 mils and could range up to a thickness of about 20 mils. Typically, the film thicknesses range from about 1.0 to about 10 mils of cured coating.

30 One process of this invention of molding and in-mold coating is illustrated in FIGS. 2 through 6. Initially the SMC charge 90 is placed on the lower die 14 when the dies are separated or the mold is open. In such

- 10 -

1 position, the pin 52 blocks the bore 68 so that the coating cannot flow into the mold cavity 16. Although this process is described in terms of the sheet molding material, it should be understood that any type of material or  
5 form of material, such as bulk molding compound, or other plastics, may be utilized.

Any thermosetting or thermoplastic plastic substrate could be used in the practice of this invention. Representative examples of thermosetting plastics include  
10 the compression and injection molded plastics, such as unsaturated polyesters as in SMC, epoxies, phenolics, silicones, polyurethanes, etc. Representative examples of useful thermoplastic materials include polyethylene, ABS, PVC, polystyrene, polypropylene, acrylics, etc.

Subsequently, as shown in FIG. 3, the press ram  
15 31 compresses the SMC 90 at a first mold cavity pressure and temperature which causes it to conform to the shape of the die cavity 16. As used herein, mold cavity pressure means the force exerted by the ram press divided by the top surface area of the formed substrate 96. In  
20 compression molding, this pressure would be in the area of 500 psi to 2000 psi. At this point, the pin 52 blocks the coating from the injection system 36.

A sequentially timed actuator 48 or other type of actuator retracts the pin 52 in FIG. 4, allowing the  
25 coating at a substantially higher pressure than the mold cavity pressure to flow through the conduit 72, chamber 70, and bore 68, into the mold cavity 16. Substantially higher pressure means a pressure sufficient to overcome the mold cavity pressure to the point where the coating  
30 spreads over the surface of the substrate. In most instances, the pressure of the injected coating will be at least two times, and more often at least four times, the

1 mold cavity pressure immediately prior to injection.  
Because of the very high pressure of the coating material,  
it coats the substrate 90 evenly without retraction  
of the die 12. It is only necessary in the timing cycle  
5 that the substrate 90 be cured to the point where it has  
formed a skin and is thus receptive to a coating.

In a compression molding process, the substrate  
polymers cross-link and shrink. As the substrate  
shrinks, the dies move toward each other to fill up the  
10 space. When the coating is subsequently injected at high  
pressures into the mold cavity 16, it acts to further  
compress the substrate 90. The addition of the coating  
at high pressure may also raise the die 12 slightly in  
spite of maintaining a ram pressure. Any movement of the  
15 dies, however, is ancillary to the injection of the coating  
and is not intentionally done and does not precede  
the step of the injection.

It is also important to note that the pressure  
is maintained in the mold cavity 16 prior to the injection  
of the coating. The actual mold cavity pressure  
20 prior to the injection may be the original molding pressure  
utilized to force the substrate into the proper form.  
Alternately, the pressure in the mold cavity  
immediately preceding the coating injection may be lower  
than the molding pressure. It is common in the molding  
25 industry to sometimes utilize a two-pressure molding  
technique. In this technique, the original high pressure  
is utilized to form the substrate and a subsequent lower  
pressure typically of about one-fourth to three-fourths  
of the forming pressure is used during the partial curing  
30 of the substrate. However, low pressure systems sometimes  
use pressures as low as 100-150 psi.

1           Because the size and shape of the dies will  
dictate the pressure of the mold cavity and the pressure  
of the coating, no one particular set of values can be  
stated. However, in an example that has been utilized,  
5   an operating pressure of about 1260 psi in the mold  
cavity was utilized with a coating pressure of about 4000  
psi. In this example, it was not necessary to reduce the  
mold cavity pressure and the coating coated all of the  
desired surfaces of the substrate evenly at a uniform  
10   thickness of about 4 mils.

          The amount of coating injected into the mold can  
be controlled in any one of several known manners. For  
example, as shown in the above-noted Ditto patent, a pre-  
determined amount of coating can be captured in a chamber  
and then released. Alternately, a timing mechanism can  
15   be used to meter the coating at a predetermined rate, and  
therefore a known volume, into the mold cavity.

          When the injection of the coating is complete,  
the pin 52 is moved downwardly, as shown in FIG. 5, by  
the actuator 48 to again block the opening to the bore  
20   68. The coated, formed substrate is then maintained in  
the mold cavity for a period of time, depending on the  
size and shape of the article, until both the coating and  
the substrate are cured. When the molding process is  
complete, the dies are separated, usually by pistons (not  
25   shown), and the finished product is removed.

          While the invention has been shown and described  
with respect to a particular embodiment thereof, this is  
for the purpose of illustration rather than limitation,  
and other variations and modifications of the specific  
30   embodiment herein shown and described will be apparent to  
those skilled in the art all within the intended spirit  
and scope of the invention. Accordingly, the patent is

- 13 -

1 not to be limited in scope and effect to the specific  
embodiment herein shown and described nor in any other  
way that is inconsistent with the extent to which the  
progress in the art has been advanced by the invention.

5

10

15

20

25

30

35

1

## 5 WHAT IS CLAIMED IS:

1. A method of molding and coating in the mold  
a substrate comprising:  
molding the substrate between at least two  
10 separable dies which form a mold cavity therebetween at a  
mold cavity pressure and temperature compatible with  
forming the substrate until the substrate reaches a con-  
dition where its surface has cured to the point that it  
is receptive to a coating;  
15 injecting a coating into the mold cavity at  
a pressure substantially in excess of what the mold cavi-  
ty pressure was immediately prior to injection while  
maintaining the dies in position whereby the coating is  
forced over the surface of and compresses the substrate;  
20 and  
curing the coated, formed substrate.

2. The process of claim 1, wherein the injec-  
tion pressure of the coating is at least two times the  
25 pressure in the mold cavity immediately before injection.

3. The process of claim 1, wherein the injec-  
tion pressure of the coating is at least four times the  
30 pressure in the mold cavity immediately before injection.

4. The process of claim 3, wherein the tempera-  
ture of the molding process is between 100°F and  
35 400°F.

1           5. The process of claim 4, wherein the substrate is a thermosetting sheet molding compound.

5           6. A method of molding and coating a thermosetting substrate in a mold having a mold cavity formed by separable dies, one of said dies having a port therein and a coating injection means operably connected to the port:

- 10           (a) opening the dies;
- (b) placing the thermosetting substrate between the dies;
- (c) closing the dies and compressing the substrate at a first pressure and temperature in the mold cavity, thereby causing the substrate to take substantially the shape of the mold cavity;
- 15           (d) at least partially curing the substrate
- (e) injecting the coating into the mold cavity through the port at a pressure substantially higher than what the positive mold cavity pressure was immediately prior to injection while the dies remain closed so that the coating covers a surface of the substrate; and
- 20           (f) curing the coated, formed substrate.
- 25

          7. The process of claim 6, wherein the substrate is cured to the point where sufficient shrinkage occurs to allow injection of the coating.

          8. The process of claim 7, wherein the substrate is cured until the surface which is to be coated forms a skin which is compatible with the coating.



1           9. The process of claim 8, wherein the formed  
substrate is partially cured at a second pressure which  
is less than the first pressure.

5           10. The process of claim 9, which further in-  
cludes opening the dies and removing the formed, coated  
substrate.

10           11. The process of claim 10, wherein the first  
pressure is between 500 and 2000 psi and the first tem-  
perature is between 100°F and 400°F.

15           12. The process of claim 11, wherein the second  
pressure is between 100 and 600 psi.

20           13. The process of claim 8, wherein the injec-  
tion pressure of the coating is at least two times the  
mold cavity pressure.

25           14. The process of claim 8, wherein the injec-  
tion pressure of the coating is at least four times the  
mold cavity pressure.

30

35

1

15. The process of claim 8, wherein injecting the coating into the mold cavity through the port includes positioning an injector pin in a first position to  
5 block the port until the substrate is at least partially cured;

moving the pin to a second position so that the coating travels through the port and into the mold cavity;

10

moving the pin back to the first position after a predetermined amount of coating sufficient to coat the desired surface of the substrate has been injected.

15

16. The process of claim 15 wherein the amount of coating injected into the mold cavity is determined by passing it through a metering pump.

20

17. The process of claim 16, wherein injecting the coating into the mold cavity includes raising the pressure of the coating to a third pressure by means of a first pump, taking the output of the first pump and raising the coating to a fourth pressure by means of a second  
25 pump which acts to meter the coating.

18. The process of claim 8, wherein the first pressure is maintained in the mold cavity until the  
30 injection of the coating has begun.

35

- 18 -

1           19. The process of claim 9, wherein the second pressure is maintained before the injection of the coating begins.

5           20. A method of molding and coating a substrate in a mold having a mold cavity formed by separable dies, the substrate being a material that will cure in the mold cavity, one of the dies having a port therein and a coating injection means operably connected to the port, comprising:

10

(a) putting the substrate into the mold cavity under environmental conditions which cause the substrate to take substantially the shape of the mold cavity;

15           (b) at least partially curing the substrate to a condition where it forms a skin which is compatible with having a coating placed upon it;

(c) injecting a coating into the mold cavity at a pressure substantially higher than the positive mold cavity pressure immediately prior to injection, the coating being injected into the mold cavity through a port in one of the dies while the dies remain closed so that the coating covers the surface of the substrate; and

20

(d) continuing to cure the coated, formed substrate.

25

21. The process of claim 20, wherein the substrate is cured to the point where shrinkage occurs and the substrate is compressible by the coating injected under high pressure.

30

**THIS PAGE BLANK (USPTO)**

FIG. 1

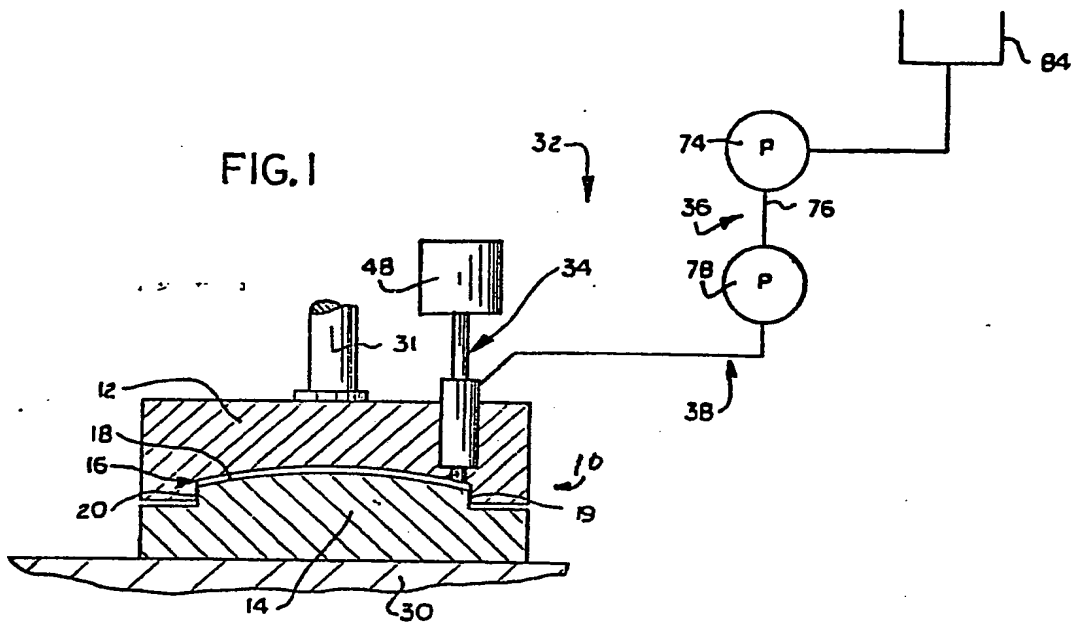
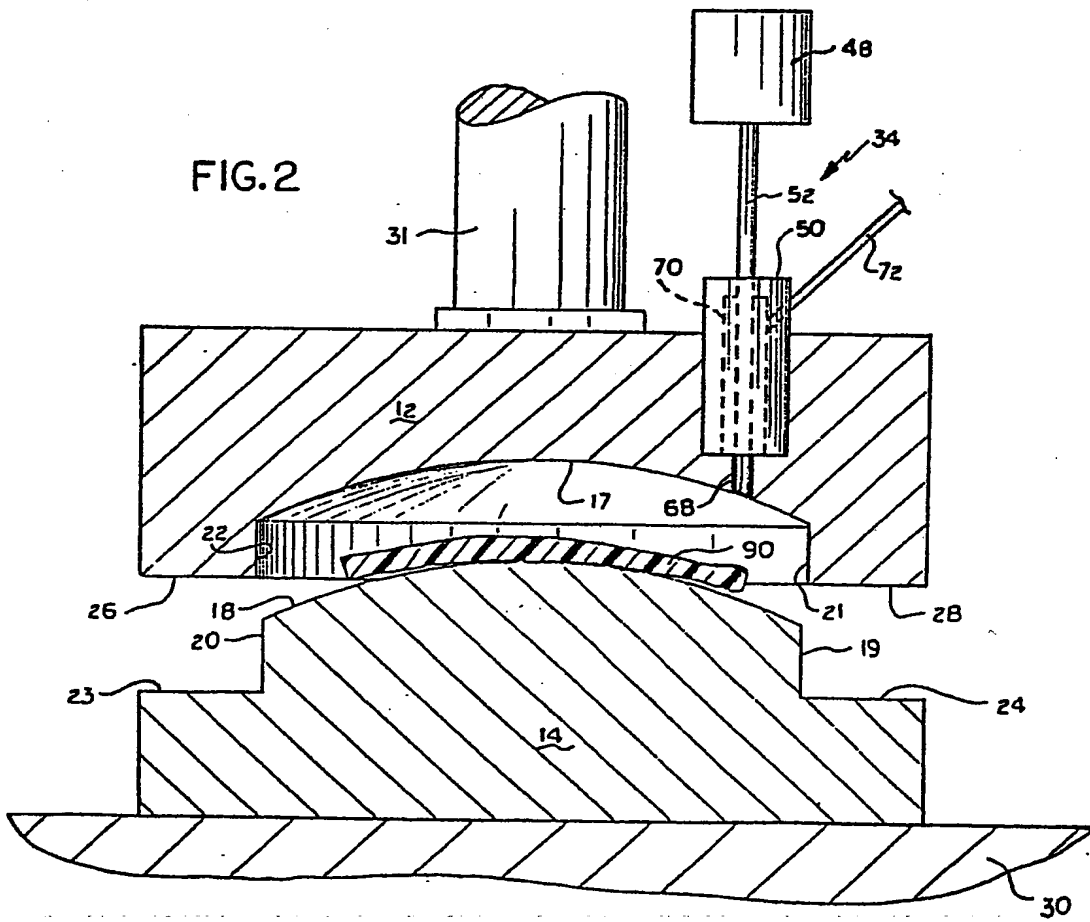


FIG. 2



**THIS PAGE BLANK (USPTO)**

FIG. 3

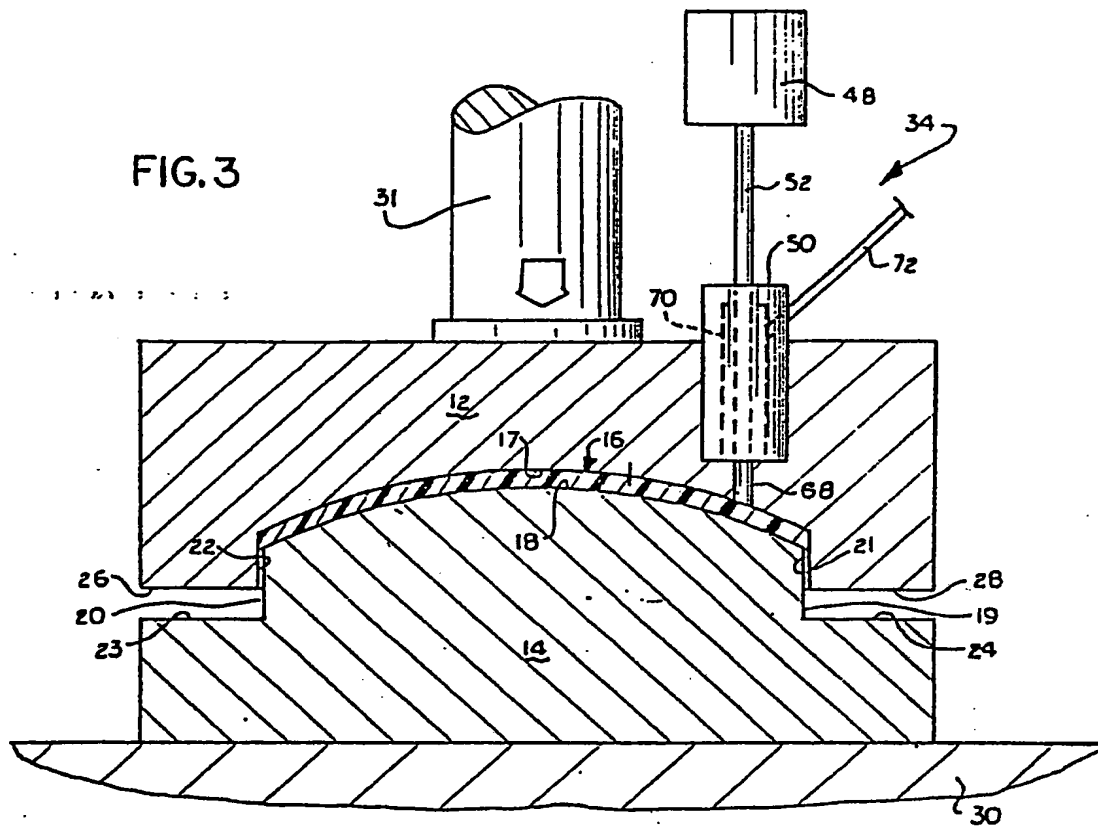
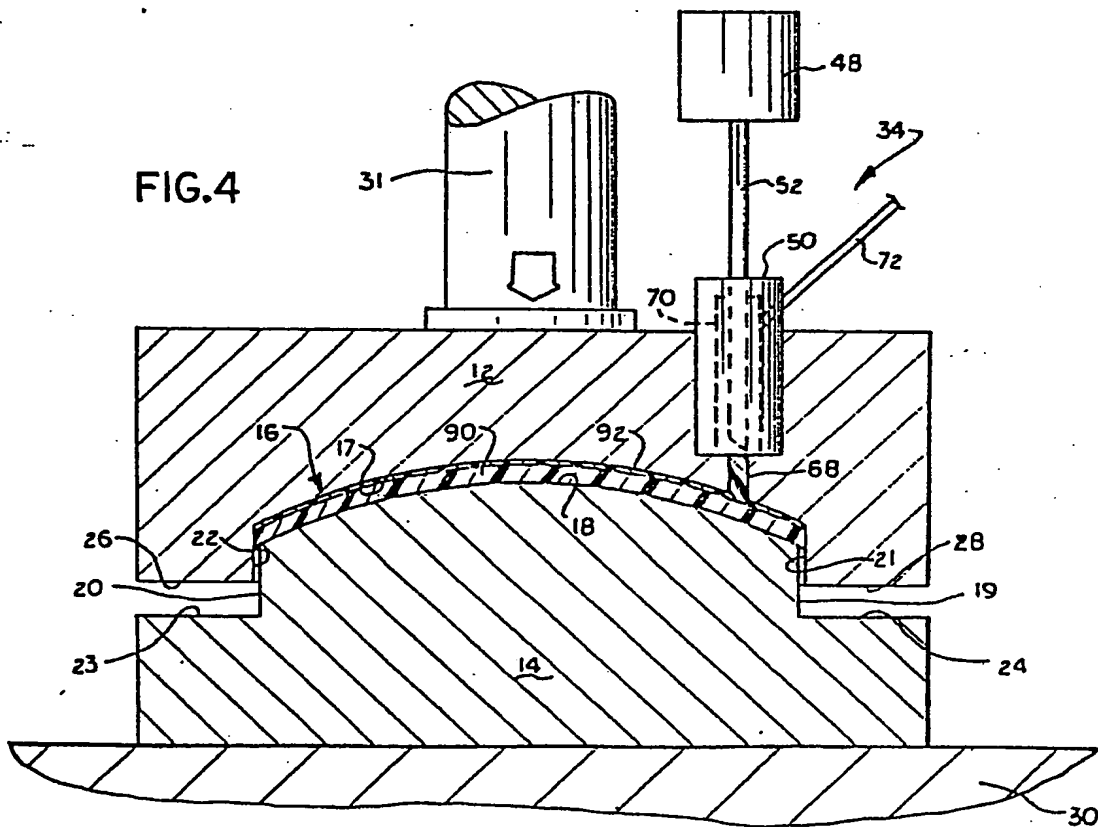


FIG. 4



**THIS PAGE BLANK (USPTO)**



FIG. 5

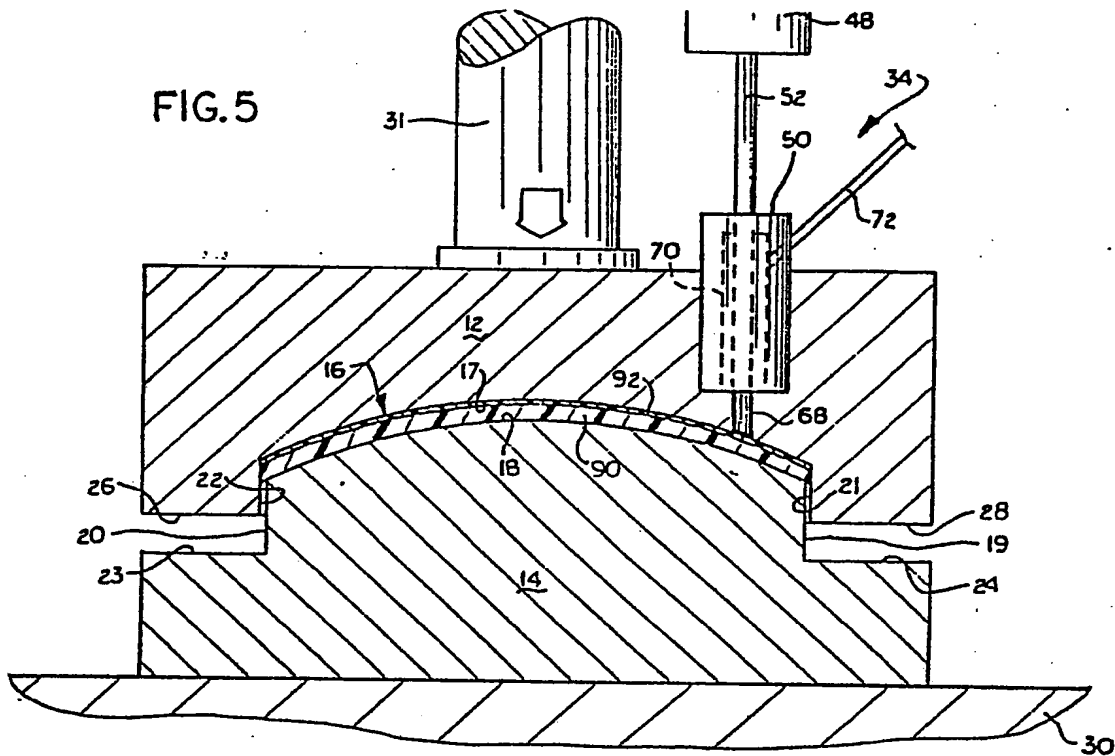
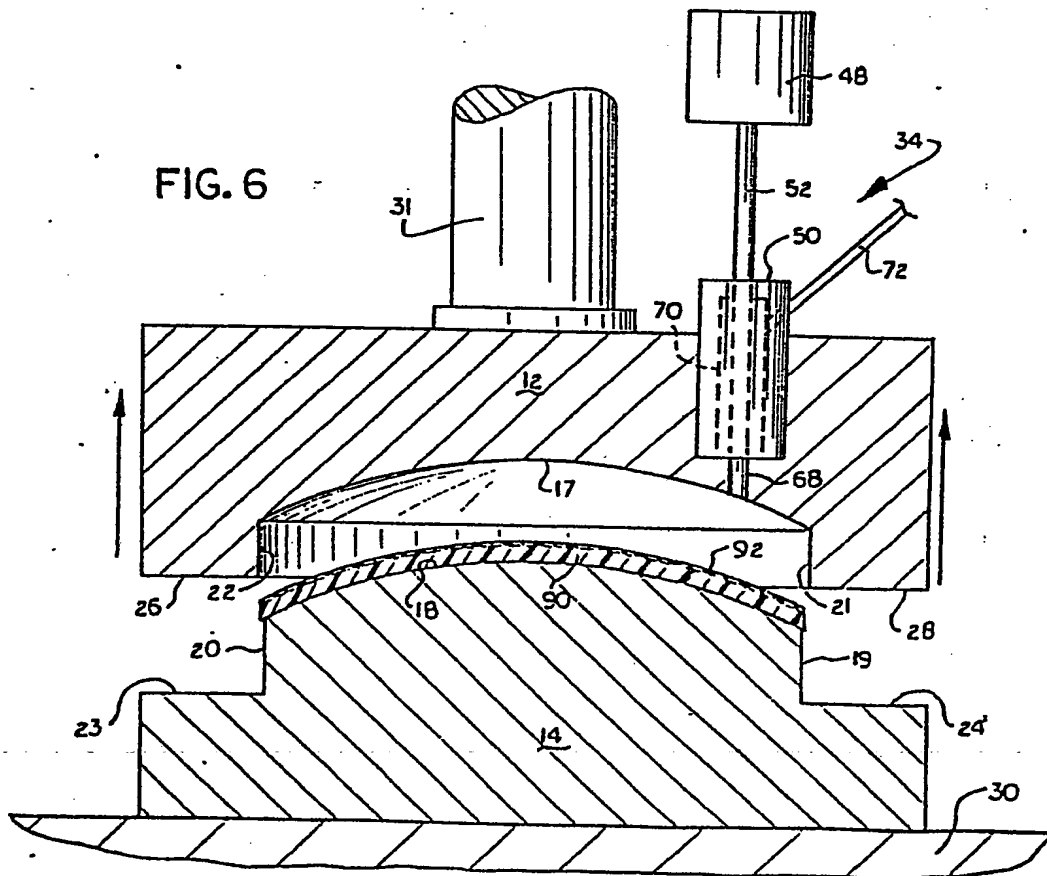


FIG. 6



THIS PAGE BLANK (USPTO)

**This Page is Inserted by IFW Indexing and Scanning  
Operations and is not part of the Official Record**

**BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- ☐ **BLACK BORDERS**
- ☐ **IMAGE CUT OFF AT TOP, BOTTOM OR SIDES**
- ☐ **FADED TEXT OR DRAWING**
- ☐ **BLURRED OR ILLEGIBLE TEXT OR DRAWING**
- ☐ **SKEWED/SLANTED IMAGES**
- ☐ **COLOR OR BLACK AND WHITE PHOTOGRAPHS**
- ☐ **GRAY SCALE DOCUMENTS**
- ☐ **LINES OR MARKS ON ORIGINAL DOCUMENT**
- ☐ **REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY**
- ☐ **OTHER:** \_\_\_\_\_

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.**

**THIS PAGE BLANK (USPTO)**